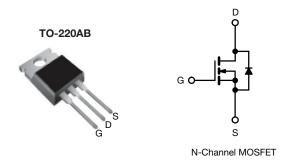
## SiHP21N60EF



**Vishay Siliconix** 

## **EF Series Power MOSFET With Fast Body Diode**



PRODUCT SUMMARY					
V <sub>DS</sub> (V) at T <sub>J</sub> max.	650				
R <sub>DS(on)</sub> max. at 25 °C (Ω)	V <sub>GS</sub> = 10 V 0.176				
Q <sub>g</sub> (Max.) (nC)	84				
Q <sub>gs</sub> (nC)	14				
Q <sub>gd</sub> (nC)	24				
Configuration	Single				

### **FEATURES**

- Fast body diode MOSFET using E series technology
- Reduced t<sub>rr</sub>, Q<sub>rr</sub>, and I<sub>RRM</sub>
- Low figure-of-merit (FOM): Ron x Qg
- Low input capacitance (Ciss)
- Increased robustness due to low Q<sub>rr</sub>
- Ultra low gate charge (Q<sub>q</sub>)
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <a href="http://www.vishay.com/doc?99912">www.vishay.com/doc?99912</a>

## **APPLICATIONS**

- Telecommunications
  - Server and telecom power supplies
- Lighting
  - High intensity discharge (HID)
  - Light emitting diodes (LEDs)
- Consumer and computing
  - ATX power supplies
- Industrial
  - Welding
  - Battery chargers
- Renewable energy
- Solar (PV inverters)
- Switch mode power suppliers (SMPS)
- Applications using the following topologies
  - LLC
  - Phase shifted bridge (ZVS)
  - 3-level inverter
  - AC/DC bridge

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Dh) free and helegen free	SiHP21N60EF-BE3		
Lead (Pb)-free and halogen-free	SiHP21N60EF-GE3		

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PARAMETER			SYMBOL	LIMIT	UNIT
Drain-source voltage			V <sub>DS</sub>	600	v
Gate-source voltage			V <sub>GS</sub>	± 30	v
Continuous drain current ( $T_{,1} = 150 \ ^{\circ}C$ )	V <sub>GS</sub> at 10 V	T <sub>C</sub> = 25 °C		21	
Continuous drain current $(1) = 150^{\circ}$ C)		T <sub>C</sub> = 100 °C	I <sub>D</sub>	14	A
Pulsed drain current <sup>a</sup>			I <sub>DM</sub>	53	
Linear derating factor				1.8	W/°C
Single pulse avalanche energy <sup>b</sup>			E <sub>AS</sub>	367	mJ
Maximum power dissipation			PD	227	W
Operating junction and storage temperature range			T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Drain-source voltage slope	T <sub>J</sub> = 125 °C		d\//d+	70	V/ns
Reverse diode dV/dt <sup>d</sup>			dV/dt	50	v/ns
Soldering recommendations (peak temperature) <sup>c</sup>	For	10 s		300	°C

Notes

a. Repetitive rating; pulse width limited by maximum junction temperature

b.  $V_{DD} = 50$  V, starting  $T_J = 25$  °C, L = 28.2 mH,  $R_g = 25 \Omega$ ,  $I_{AS} = 5.1$  A

- c. 1.6 mm from case
- d.  $I_{SD} \leq I_D$ , dI/dt = 900 A/µs, starting T<sub>J</sub> = 25 °C

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THERMAL RESISTANCE RATINGS				
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum junction-to-ambient	R <sub>thJA</sub>	-	62	°C/W
Maximum junction-to-case (drain)	R <sub>thJC</sub>	-	0.55	0/10

PARAMETER	SYMBOL	TES	T CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static							<b>I</b>
Drain-source breakdown voltage	V <sub>DS</sub>	V <sub>GS</sub> =	= 0 V, I <sub>D</sub> = 250 μA	600	-	-	V
V <sub>DS</sub> temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I <sub>D</sub> = 1 mA		-	0.59	-	V/°C
Gate-source threshold Voltage (N)	V <sub>GS(th)</sub>	V <sub>DS</sub> =	: V <sub>GS</sub> , I <sub>D</sub> = 250 μA	2.0	-	4.0	V
		$V_{GS} = \pm 20 V$		-	-	± 100	nA
Gate-source leakage	I <sub>GSS</sub>	,	V <sub>GS</sub> = ± 30 V	-	-	± 1	μA
Zaus auto usltana dusia suuraat		V <sub>DS</sub> =	$V_{DS} = 480 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		-	1	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 480 V	′, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 125 °C	-	-	500	μA
Drain-source on-state resistance	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 11 A	-	0.153	0.176	Ω
Forward transconductance	9 <sub>fs</sub>	V <sub>DS</sub>	= 30 V, I <sub>D</sub> = 11 A	-	7	-	S
Dynamic							
Input capacitance	C <sub>iss</sub>		$V_{GS} = 0 V$ ,	-	2030	-	
Output capacitance	C <sub>oss</sub>	$V_{DS} = 100 V,$		-	105	-	1
Reverse transfer capacitance	C <sub>rss</sub>		f = 1 MHz	-	5	-	
Effective output capacitance, energy related <sup>a</sup>	C <sub>o(er)</sub>			-	86	-	pF
Effective output capacitance, time related <sup>b</sup>	C <sub>o(tr)</sub>	$V_{GS} = 0$	V, $V_{DS} = 0$ V to 480 V	-	299	-	
Total gate charge	Qq			-	56	84	
Gate-source charge	Q <sub>gs</sub>	V <sub>GS</sub> = 10 V	I <sub>D</sub> = 11 A, V <sub>DS</sub> = 480 V	-	14	-	nC
Gate-drain charge	Q <sub>gd</sub>			-	24	-	
Turn-on delay time	t <sub>d(on)</sub>			-	21	42	
Rise time	t <sub>r</sub>	V <sub>DD</sub> = 480 V, I <sub>D</sub> = 11 A		-	31	62	1
Turn-off delay time	t <sub>d(off)</sub>		9.1 Ω, V <sub>GS</sub> = 10 V	-	59	89	ns
Fall time	t <sub>f</sub>			-	27	54	
Gate input resistance	R <sub>g</sub>	f = 1 MHz, open drain		0.2	0.56	1.2	Ω
Drain-Source Body Diode Characteristic	s	•			•	•	•
Continuous source-drain diode current	١ <sub>S</sub>	MOSFET symbol showing the integral reverse p - n junction diode		-	-	21	
Pulsed diode forward current	I <sub>SM</sub>			-	-	53	- A
Diode forward voltage	V <sub>SD</sub>	T <sub>J</sub> = 25 °C	C, I <sub>S</sub> = 11 A, V <sub>GS</sub> = 0 V	-	0.9	1.2	V
Reverse recovery time	t <sub>rr</sub>			-	135	270	ns
Reverse recovery charge	Q <sub>rr</sub>		5 °C, I <sub>F</sub> = I <sub>S</sub> = 11 A, 00 A/µs, V <sub>B</sub> = 400 V	-	0.76	1.52	μC
Reverse recovery current	I <sub>RRM</sub>		$100 \text{ Av} \mu\text{S}, \text{ v}_{\text{R}} = 400 \text{ v}$	-	11	-	A

## Notes

e.  $C_{oss(er)}$  is a fixed capacitance that gives the same energy as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ 

f.  $C_{oss(tr)}$  is a fixed capacitance that gives the charging time as  $C_{oss}$  while  $V_{DS}$  is rising from 0 % to 80 %  $V_{DS}$ 



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## TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

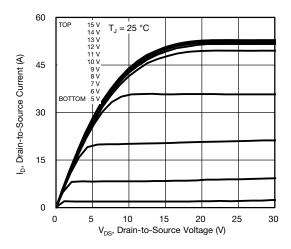


Fig. 1 - Typical Output Characteristics, T<sub>J</sub> = 25 °C

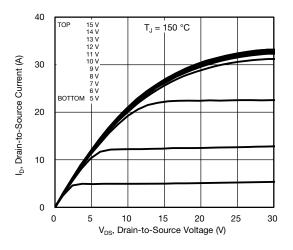


Fig. 2 - Typical Output Characteristics,  $T_J$  = 150 °C

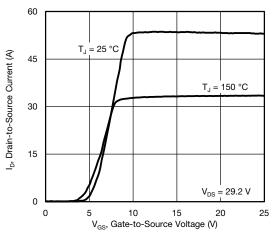


Fig. 3 - Typical Transfer Characteristics

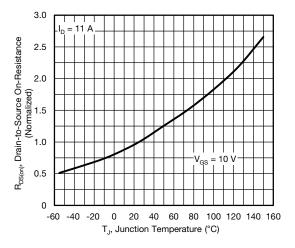


Fig. 4 - Normalized On-Resistance vs. Temperature

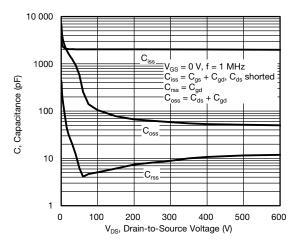
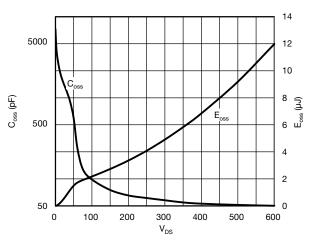
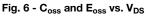


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage





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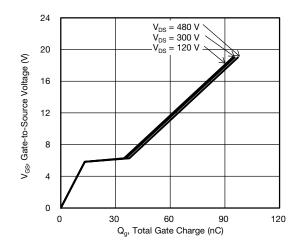


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

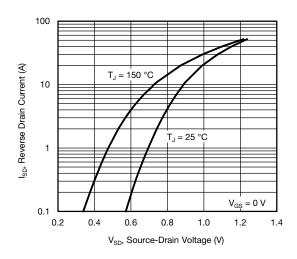


Fig. 8 - Typical Source-Drain Diode Forward Voltage

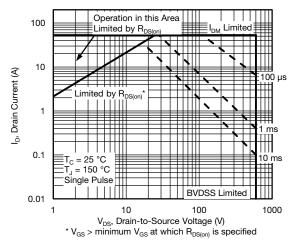


Fig. 9 - Maximum Safe Operating Area

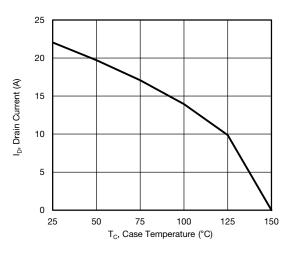


Fig. 10 - Maximum Drain Current vs. Case Temperature

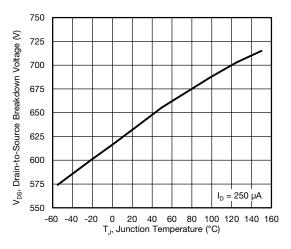


Fig. 11 - Typical Drain-to-Source Voltage vs. Temperature

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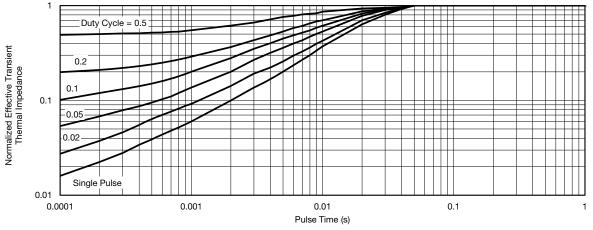
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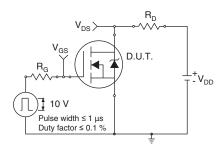


Fig. 13 - Switching Time Test Circuit

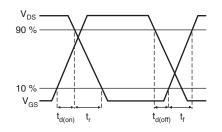


Fig. 14 - Switching Time Waveforms

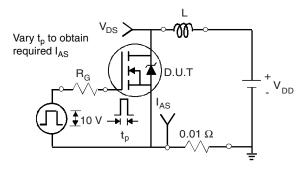


Fig. 15 - Unclamped Inductive Test Circuit

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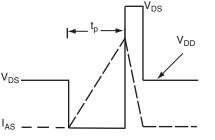


Fig. 16 - Unclamped Inductive Waveforms

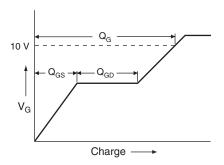
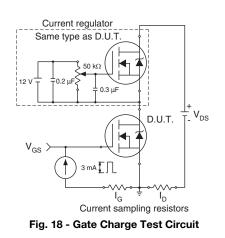


Fig. 17 - Basic Gate Charge Waveform





#### Peak Diode Recovery dV/dt Test Circuit

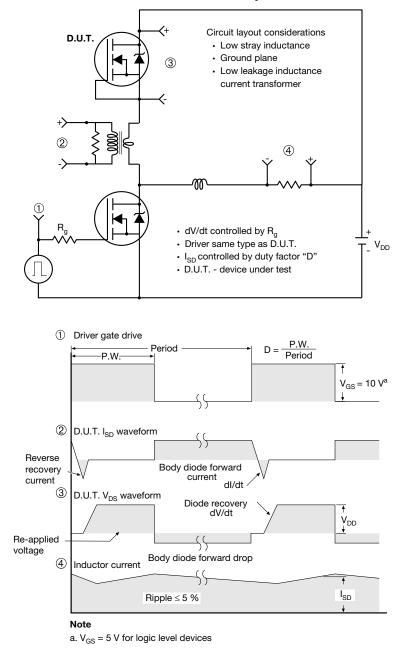


Fig. 19 - For N-Channel

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TO-220-1



DIM.	MILLIN	IETERS	INC	HES
DIM.	MIN.	MAX.	MIN.	MAX.
А	4.24	4.65	0.167	0.183
b	0.69	1.02	0.027	0.040
b(1)	1.14	1.78	0.045	0.070
С	0.36	0.61	0.014	0.024
D	14.33	15.85	0.564	0.624
E	9.96	10.52	0.392	0.414
е	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.10	6.71	0.240	0.264
J(1)	2.41	2.92	0.095	0.115
L	13.36	14.40	0.526	0.567
L(1)	3.33	4.04	0.131	0.159
ØP	3.53	3.94	0.139	0.155
Q	2.54	3.00	0.100	0.118

### Note

• M\* = 0.052 inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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